30V N-Channel Trench Power MOSFET

General Description

The SJP30N070 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

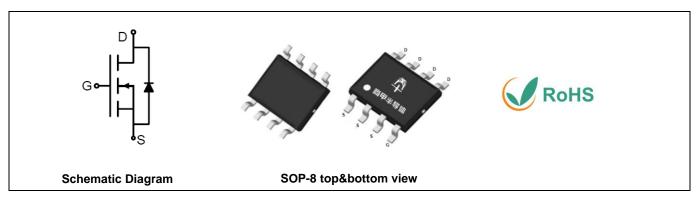
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	30	V
R _{DS(ON)_TYP}	6.9	mΩ
I _D	15	A
Q _G	21.6	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity	
SJP30N070	SJP30N070	SOP-8	Tape	\	/	4000 Pcs	

Table 1. Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	30	V
V _G S	Gate-Source Voltage (V _{DS} =0V)	±20	V
I-	Drain Current-Continuous(T _A =25°C)	15	А
I _D	Drain Current-Continuous(T _A =100℃)	9	А
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	60	А
D	Maximum Power Dissipation(T _A =25°ℂ)	2.5	W
P _D	Maximum Power Dissipation(T _A =100°C)	1.2	W
E _{AS}	Avalanche energy (Note 2)	95	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient		45	°C/W



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Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	•					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
	7 0 1 1/1 1 2 1 0 1	V _{DS} =30V, V _{GS} =0V T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =125℃			100	μΑ
lgss	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1		2.5	V
g FS	Forward Transconductance	V _{DS} =5V, I _D =20A		18		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A T _J =25℃		6.9	8.3	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =15A T _J =25°C		9.2	12.2	mΩ
Dynamic Chara	octeristics			•		
Ciss	Input Capacitance			1264		pF
Coss	Output Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		254		pF
Crss	Reverse Transfer Capacitance			201		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.8		Ω
Switching Para	meters					
t _{d(on)}	Turn-on Delay Time			12		nS
t _r	Turn-on Rise Time	V _{GS} =10V, V _{DS} =15V,		2.4		nS
t _{d(off)}	Turn-Off Delay Time	$R_L=0.75\Omega$, $R_{GEN}=3\Omega$		30.4		nS
t _f	Turn-Off Fall Time			4		nS
Qg	Total Gate Charge			21.6		nC
Qgs	Gate-Source Charge	V _{GS} =10V, V _{DS} =15V, I _D =20A		2.7		nC
Q_gd	Gate-Drain Charge			4.7		nC
Source-Drain D	liode Characteristics					
I _{SD}	Source-Drain Current (Body Diode)				15	А
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=500A/μs		19.4		ns
Qrr	Reverse Recovery Charge	Ir=20A, dI/dt=500A/μs		11.6		nC

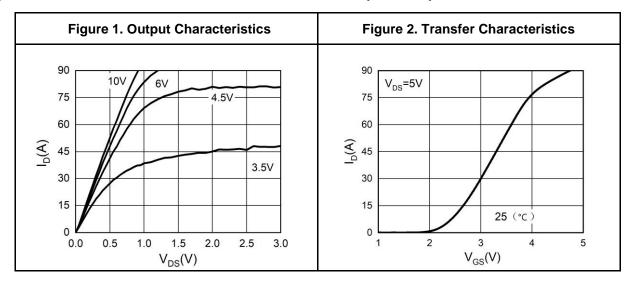
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

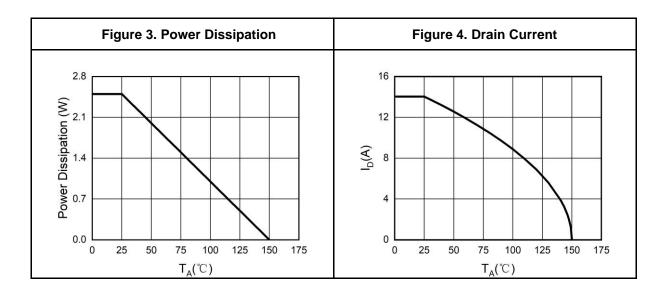
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=30V$, $V_{G}=10V$, $Rg=25\Omega$, L=0.5mH.

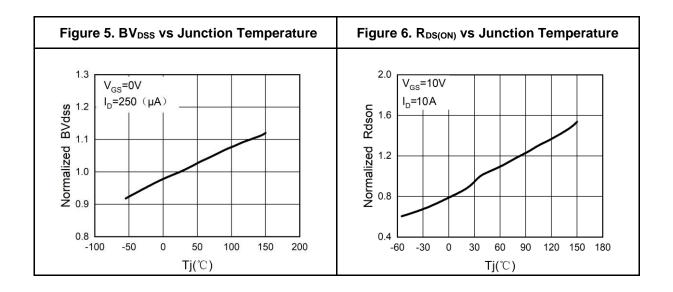
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Typical Electrical And Thermal Characteristics (Curves)

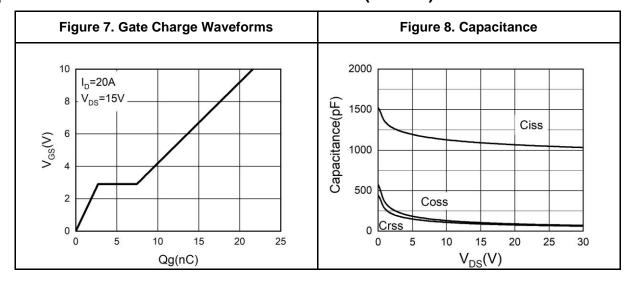


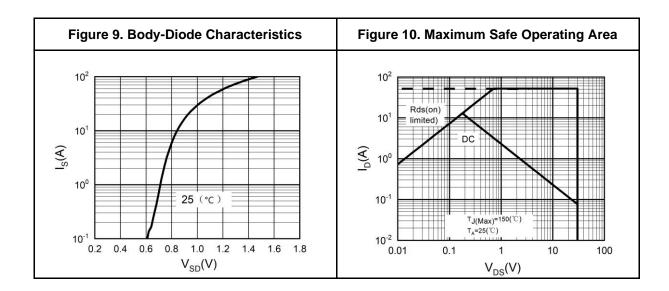






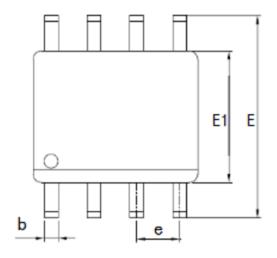
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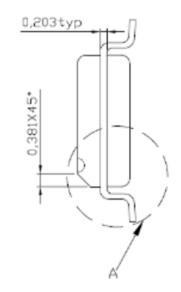


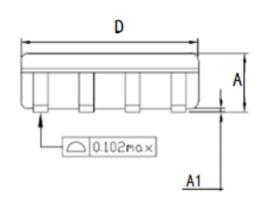


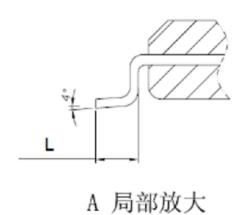


SOP-8 Package Information









Cumbal	Dimer	nsions In Millimeters			
Symbol	Min.	Nom.	Max		
Α	1.35	1.55	1.75		
A1	0.1	0.15	0.2		
b	0.346	0.406	0.466		
D	4.8	4.89	4.98		
E	5.75	6.00	6.25		
E1	3.81	3.90	3.99		
е	1.27TYP				
L	0.406	0.838	1.27		

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